



Part Number:101-00318-**
SIM + Micro SD P/P Card Conn.

- Push-push eject type
- SMT
- Application for mobile phones

- 1.Materials:**
 Housing: High temperature thermoplastic, UL 94V-0 rated.
 Contact: Copper alloy
 Cover: SUS304 over nickel plating (50U" min)
- 2.Contact finish:**
 Selective 1~15u" gold plating on contact area, tin 160u" plating at solder tail, over nickel plating (50u"min)
- 3.Electrical specifications:**
 Voltage Rating: 100VAC
 Current Rating: 0.5A per contact
 Dielectric strength: 500VAC initial and 250VAC final for one minute
 Insulation Resistance: 1000MΩ min at 500VDC
 Contact Resistance: 100mΩ max at 100mA
 Operating temperature: -25°C~+70°C
- 4.Mechanical specifications:**
 Durability: 5000cycles.
 Micro SD Card Mating force: 13.8N max.
 Micro SD Card Unmating force: 1N max
 Sim Card Mating force: 10N max.
 Sim Card Unmating force: 0.3N max
- 5.RoHS Compliant**

